



BUCKET NO.: FCI-2580
Application No.: 10/010,149
Office Action Dated: July 16, 2003

PATENT

I. Amendments to the Specification:

Please replace the paragraph beginning at page 7, line 4 with the following replacement paragraph.

-- Dielectric 40 is substantially planar and may comprise polyimide or the like. A low dielectric material is typically desired for high speed communications. Therefore, dielectric 40 may comprise polyimide; however, other materials may be used, typically, other low dielectric materials. An illustrative dielectric 40 is approximately 0.25 mm thick; however, various thicknesses may be employed depending on the desired impedance characteristics between conductors 50 and ground plane 30. Dielectric 40 comprises a recess 42 at an end of its planar surface proximate to conductor 50 for receiving a solder ball 43 for a ball grid array attachment, for example, of conductor 50 to circuit board 90. While solder ball connection of conductor 50 to circuit board 90 is illustrated, other techniques are contemplated. --

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